

JOIN
US



STRONG SUPPLY CHAIN
to support your novel design



FAST RAMP UP
from design to market



STRICT IP PROTECTION
with Assembly services

ADVANCED PACKAGING

YOUR GO TO
PARTNER FOR COMPLEX CO-DEVELOPMENT

PACKAGING
THE
FUTURE
TODAY

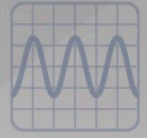


IBM[®]

www.ibm.com/assembly

ASSEMBLY AND TEST

COMPLETE DESIGN FOR SYSTEM OPTIMISATION, MANUFACTURING, DIAGNOSTICS AND TESTS



Design for test
Enhanced wafer test coverage
Test in assembly flow
On demand rework capability
Yield management

LAMINATE DESIGN FOR SPECIALITY APPLICATIONS FORM FACTOR FLEXIBILITY

High performance computing
Networking (satellite, antenna, optical, RF, 5G)
ASICs



Advanced ground rules

Chip to capacitor	< 1 mm
Chip to laminate edge	0.7 mm
Chip to chip	0.2 mm
Capacitor to capacitor	0.16 mm (0201)

MATERIAL SET AND DESIGN

High power and high performance
Assembly approach supporting but not limited to 400A-400W
Ground rules for proven reliability



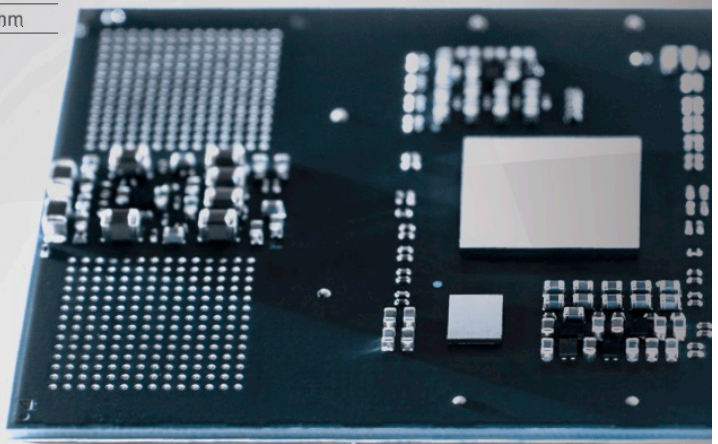
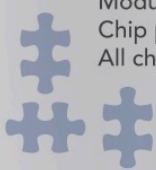
Comparative signal losses at 28 GHz

Commercial High End	-0,15 dB/mm
IBM Current Node	-0,10 dB/mm
IBM Advanced Solution	-0,08 dB/mm

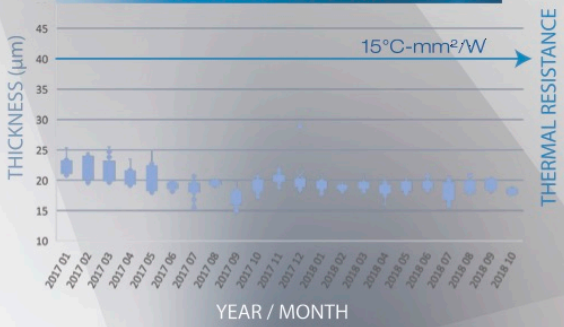
* Best practice and roadmap (40% improvement)

HETEROGENEOUS INTEGRATION

High complexity SiP
Varied and very densely mounted components
Modularity for cost saving
Chip partitioning
All chips nodes from any foundries



MONTHLY BONDLINE DATA



EFFECTIVE THERMAL AND WARPAGE SOLUTION

